

M61250BFP

NTSC 1 chip TV signal processor

REJ03F0088-0100Z

Rev.1.0

Sep.23.2003

Description

The M61250BFP is a single-chip semiconductor integrated circuit that contains the signal processing for NTSC color television.

All of the signal processing circuits for video intermediate frequencies, vocal intermediate frequencies, video, color, and polarization, as well as I²C bus control, are built in, and television sets ranging from popular-class to medium-grade sets are supported. Moreover, the M37150 8-bit microcomputer for the television and the interconnection pin are opposite each other, so that less space is required for mounting.

Features

- No VCO coil for VIF required
- Internal unregulated vocal demodulator
- PLL-SPLIT SIF system for FM radio
- Fsc output
- ACL or ABCL can be selected
- Internal horizontal oscillation probe
- Internal perpendicular sawtooth wave generator
- Internal self-diagnosis function
- Internal black peak hold, AFC2, killer filter
- H & V pulse output for OSD
- Internal reset circuit and clock output for microcomputer use
- Internal 5 V and 8 V regulators

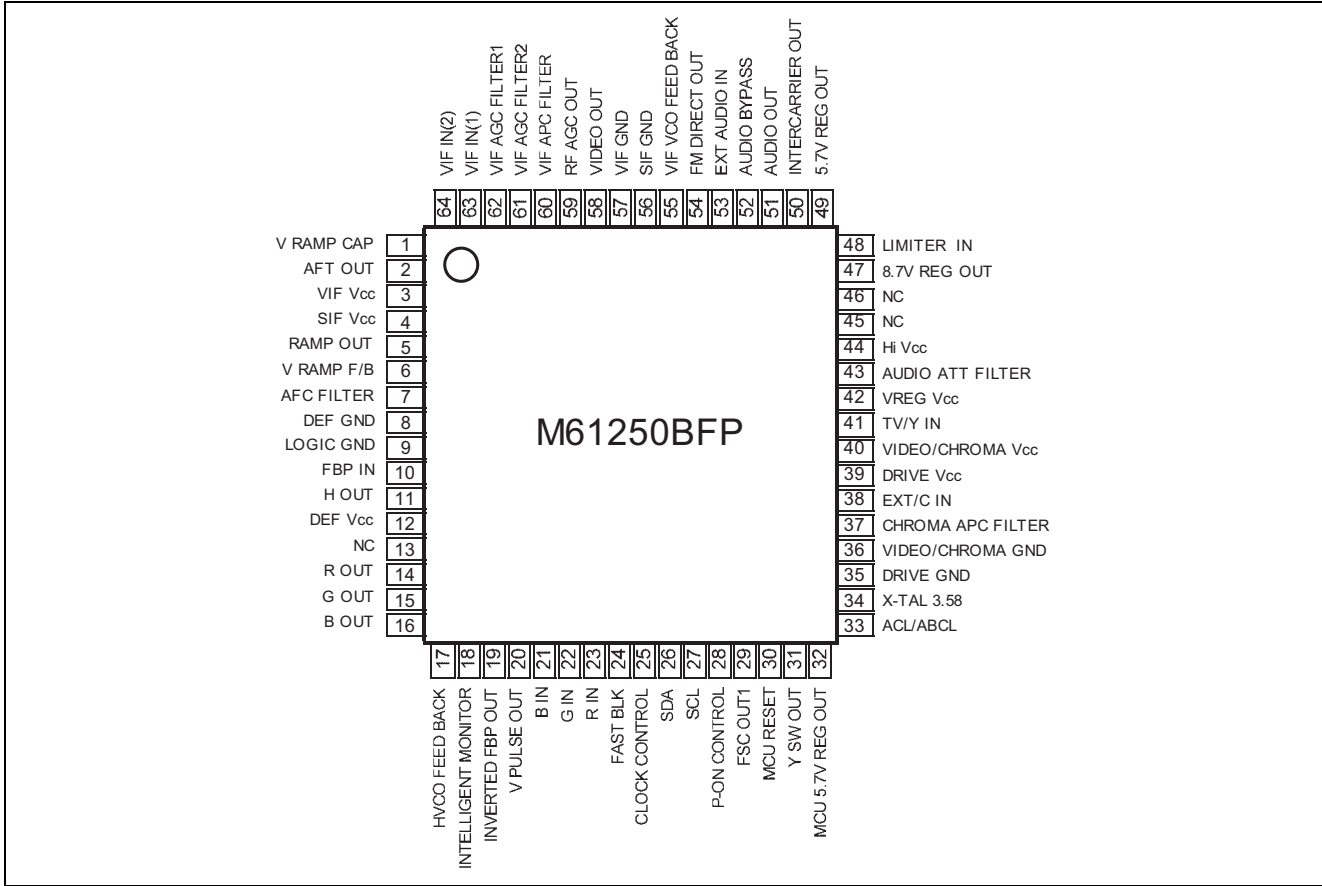
Applications

- NTSC color television receivers

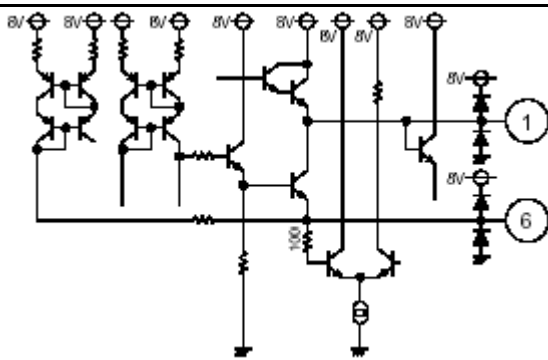
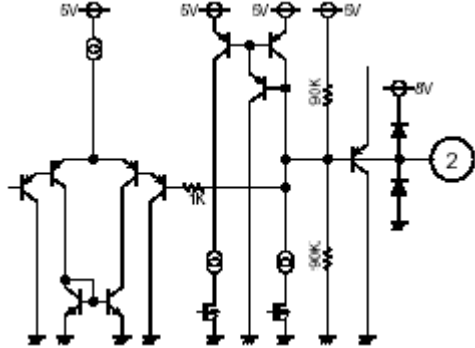
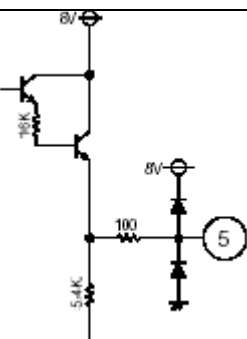
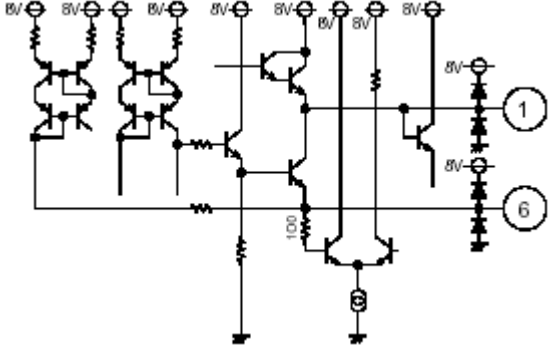
Recommended Operating Conditions

- Power supply voltage range:
 - 4.75 V to 5.25 V (Pins 3, 4, 39, 40)
 - 7.6 V to 8.4 V (Pins 12, 44)
 - 8.3 V to 9.1 V (Pin 42)
- Recommended power supply voltage:
 - 5.0 V (Pins 3, 4, 39, 40)
 - 8.0 V (Pins 12, 44)
 - 8.7 V (Pin 42)

Pin Configuration (Top View)



Pin Explanations

Pin No.	Name	Pin peripheral circuit	DC voltage (V)
1	V RAMP CAP		
2	AFT OUT		0.3 to 4.7
3	VIF V _{CC}		5.0 V
4	SIF V _{CC}		
5	RAMP OUT		4.6
6	V RAMP FEED BACK		

Pin Explanations (cont)

Pin No.	Name	Pin peripheral circuit	DC voltage (V)
7	AFC FILTER		3.5 V
8	DEF GND		
9	LOGIC GND		
10	FBP IN		V _{TH} : 2.0 V (FBP Vth L = OFF) V _{TH} : 1.0 V (FBP Vth L = ON)
11	H OUT		V _{OL} : 0.0 V V _{OH} : 5.4 V
12	DEF V _{CC}		
13	NC		
14	R OUT		
15	G OUT		
16	B OUT		

Pin Explanations (cont)

Pin No.	Name	Pin peripheral circuit	DC voltage (V)
17	H VCO FEEDBACK		3.0 V
18	INTELLIGENT MONITOR		
19	INV FBP OUT		V _{OL} : 0.0 V V _{OH} : 5.0 V
20	V PULSE OUT		V _{OL} : 0.0 V V _{OH} : 5.0 V

Pin Explanations (cont)

Pin No.	Name	Pin peripheral circuit	DC voltage (V)
21 22 23	B IN G IN R IN		(1) Digital OSD V_{IL} : 0.0 V V_{IH} : 3.0 V (2) Analog OSD 0.7 Vp-p
24	FAST BLK		0.0-0.5 V: INT RGB 1.5-3.0 V: H TONE 4.0-5.0 V: EXT RGB
25	CLK CONTROL		V_{TH} : 3.0 V
26	SDA		V_{IL} : 0.75 V V_{IH} : 4.25 V

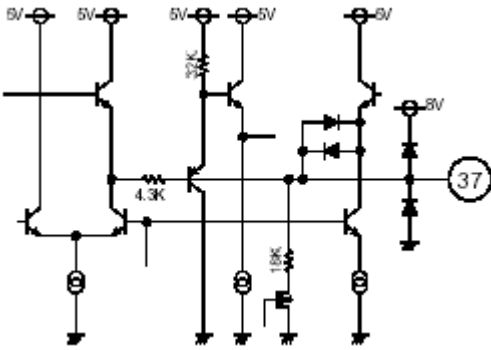
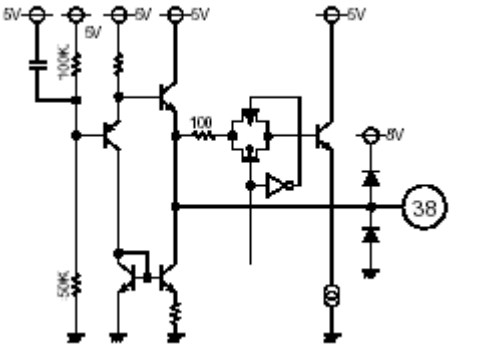
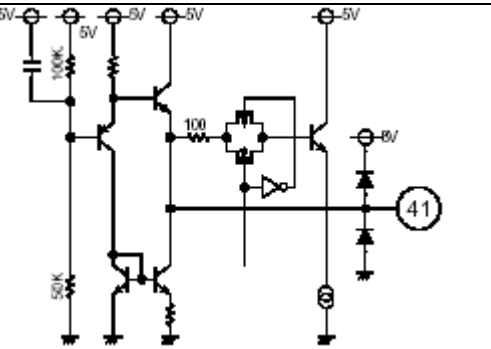
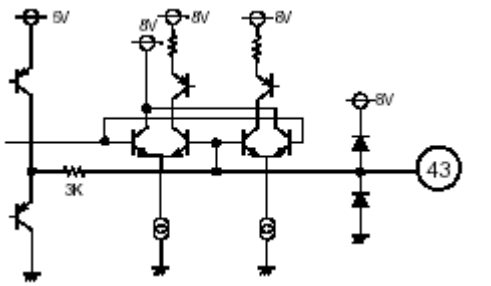
Pin Explanations (cont)

Pin No.	Name	Pin peripheral circuit	DC voltage (V)
27	SCL		V_{IL} : 0.75 V V_{IH} : 4.25 V
28	POWER ON CONTROL		V_{TH} : 3.0 V
29	fsc OUT 1		3.0 V
30	MCU RESET		H : 5.0 V L : 0.0 V

Pin Explanations (cont)

Pin No.	Name	Pin peripheral circuit	DC voltage (V)
31	Y SW OUT		1.7 V
32	MCU 5.7 VREG OUT		5.7 V
33	ACL/ABCL		5.0 V
34	X-TAL 3.58		3.3 V
35	DRIVE GND		0.0 V
36	Video/Chroma GND		0.0 V

Pin Explanations (cont)

Pin No.	Name	Pin peripheral circuit	DC voltage (V)
37	CHROMA APC FILTER		3.2 V
38	EXT/C IN		1.7 V
39	DRIVE V _{CC}	—————	5.0 V
40	Video/Chroma V _{CC}	—————	
41	TV/Y IN		1.7 V
42	VREG V _{CC}	—————	8.7 V
43	AUDIO ATT FILTER		2.75 V to 3.25 V
44	Hi V _{CC}	—————	8 V
45	NC	—————	
46		—————	

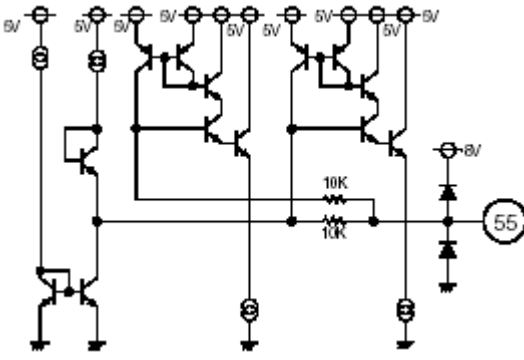
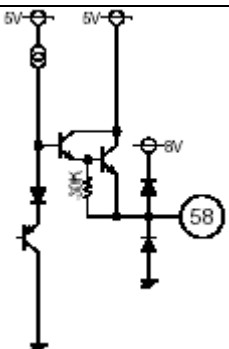
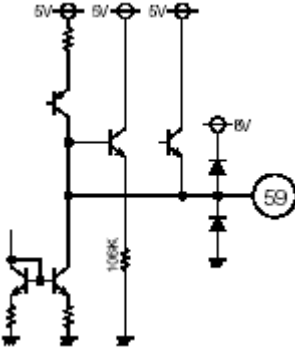
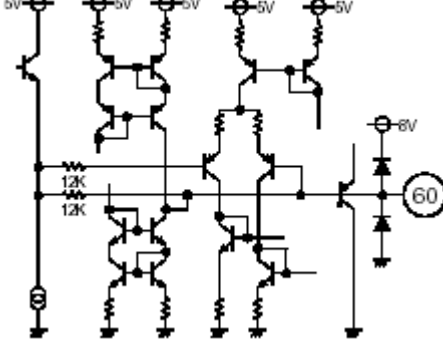
Pin Explanations (cont)

Pin No.	Name	Pin peripheral circuit	DC voltage (V)
47	8.7 VREG OUT		8.7 V
48	LIMITER IN		2.5 V
49	5.7 VREG OUT		5.7 V
50	INTER CARRIER OUT		2.3 V

Pin Explanations (cont)

Pin No.	Name	Pin peripheral circuit	DC voltage (V)
51	AUDIO OUT		2.3 V
52	AUDIO BYPASS		2.3 V
53	EXT AUDIO IN		3.0 V
54	FM DIRECT OUT		3.0 V

Pin Explanations (cont)

Pin No.	Name	Pin peripheral circuit	DC voltage (V)
55	VIF VCO FEEDBACK		3.0 V
56	SIF GND	-----	
57	VIF GND	-----	
58	VIDEO OUT		2.7 V
59	RF AGC OUT		0.3 to 4.7 V
60	VIF APC FILTER		3.0 V

Pin Explanations (cont)

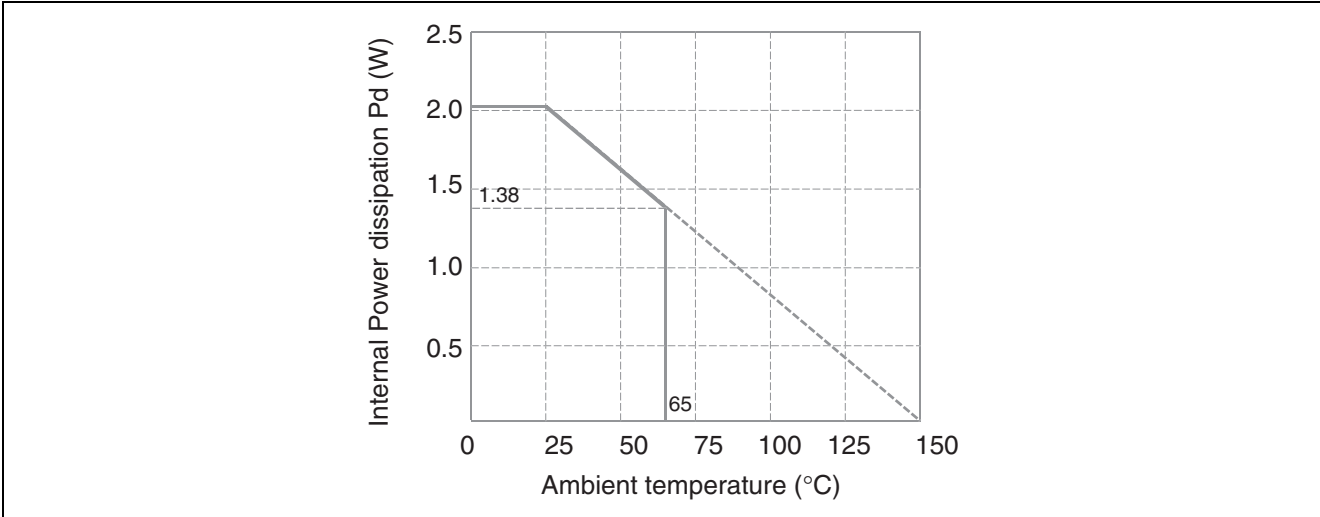
Pin No.	Name	Pin peripheral circuit	DC voltage (V)
61 62	VIF AGC FILTER 2 VIF AGC FILTER 1		2.3 V
63 64	VIF IN (1) VIF IN (2)		1.6 V

Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Rating	Unit
Power supply voltage	VCC	6.0, 10.0	V
Internal power dissipation	Pd	2026	mW
Thermal derating	Kt	16.2	mW/°C
Ambient operating temperature	Topr	-20 to +65	°C
Storage temperature	Tstg	-40 to +150	°C

Thermal Derating (Maximum Ratings)



I²C Bus Table

1. SLAVE ADDRESS= BAH(WRITE), BBH(READ)

A6	A5	A4	A3	A2	A1	A0	R/W
1	0	1	1	1	0	1	1/0

2. WRITE TABLE(input bytes)

SUB ADDRESS		DATA								INITIAL		
HEX	BIN	D7	D6	D5	D4	D3	D2	D1	D0			
00H	00000000	(inhibited)	RF Delay Adj								40H	
		0	1	0	0	0	0	0	0			
01H	00000001	(inhibited)	VIF VCO ADJ								20H	
		0	0	1	0	0	0	0	0			
02H	00000010	Video Mute	Audio EXT	C. Clip level	TRAP Off	Video T Sharp	ABCL	Black Stre. Off	Take Off	00H		
		0	0	0	0	0	0	0	0			
03H	00000011	Audio Mute	Audio ATT								00H	
		0	0	0	0	0	0	0	0			
04H	00000100	ABCL Gain	AFT Defeat	Video Tone								20H
		0	0	V1	V0	V0	V0	V0	V0			
05H	00000101	EXTRGB C. Clip	Contrast Control								40H	
		V0	V1	V0	V0	V0	V0	V0	V0			
06H	00000110	VIF Video Out Gain			Y/C	EXT	Y DL Fine Adj	Y DL Time Adj			80H	
		1	0	0	V0	V0	0	0	0			
07H	00000111	VIF Defeat	Tint Control								40H	
		0	V1	V0	V0	V0	V0	V0	V0			
08H	00001000	Blue Back	Color Control								40H	
		V0	V1	V0	V0	V0	V0	V0	V0			
09H	00001001	HV BLK OFF	VOUT STOP	FSC FREE	HTONE SW	(inhibited)					04H	
		0	0	0	0	0	1	0	0			
0AH	00001010	Brightness Control								80H		
		V1	V0	V0	V0	V0	V0	V0	V0			
0BH	00001011	(inhibited)	Drive(R)								40H	
		0	1	0	0	0	0	0	0			
0CH	00001100	(inhibited)	Drive(B)								40H	
		0	1	0	0	0	0	0	0			
0DH	00001101	Cut Off(R)								80H		
		1	0	0	0	0	0	0	0			
0EH	00001110	Cut Off(G)								80H		
		1	0	0	0	0	0	0	0			
0FH	00001111	Cut Off(B)								80H		
		1	0	0	0	0	0	0	0			
10H	00010000	White Back	V-free	(inhibited)				H VCO Adj			24H	
		0	0	1	0	0	1	0	0			
11H	00010001	(inhibited)	V-Size								20H	
		0	0	1	0	0	0	0	0			
12H	00010010	Monitoring				Gamma Control		TRAP Fine Adj			00H	
		0	0	0	0	0	0	0	0			
13H	00010011	H-free	V.1Window	YSW LPF	H Start	Service SW	V Shift				00H	
		0	0	0	0	0	0	0	0			
14H	00010100	Black Stretch Discharge		Black Stretch Charge		S.Slice Down2	S.Slice Down1	(inhibited)			03H	
		0	0	0	0	0	0	1	1			
15H	00010101	AFC1 Gain	AFC2 Gain	OSD level	Analog OSD	US/JPN SW			Killer level	00H		
		0	0	0	0	0	0	0	0			
16H	00010110	VSYNCDDET	Aoto slice down	FBP Vth L	AFC2 H Phase					90H		
		1	0	0	1	0	0	0	0			
17H	00010111	(reserved)								40H		
		0	V1	V0	V0	V0	V0	V0	V0			
18H	00011000	Test1			(inhibited)					00H		
		0	0	0	0	0	0	0	0			
19H	00011001	BGPFBP OFF	Test2		(inhibited)					00H		
		0	0	0	0	0	0	0	0			
1AH	00011010	Test3			(inhibited)					00H		
		0	0	0	0	0	0	0	0			
1BH	00011011	(inhibited)								00H		
		0	0	0	0	0	0	0	0			
1CH	00011100	TEST4	VFREE INT	(inhibited)		VBLKSHIFT ON	VBLK SHIFT			04H		
		0	0	0	0	0	1	0	0			

NOTE: V0 / V1 ==> V- LATCH BIT

3. READ TABLE (output bytes)

SUB ADDRESS		D7	D6	D5	D4	D3	D2	D1	D0
00H	00000000	KILLERB	(not assigned)	VCOINB	STDETB	AFT0	AFT1	HCOINB	(not assigned)

Bus Functions

WRITE

	FUNCTION	BIT	SUB ADD	DATA	DISCRIPTION	INI- TIAL	NOTE
VIF	RF delay adj	7	00H	D0-D6	RF AGC delay point adjustment	40H	
SIF	VIF VCO adj	6	10H	D0-D5	VIF VCC free-running frequency adjustment (adjust by setting VIF Defeat = 1 to center the AFT output)	20H	
	VIF freq. 58.75	1	01H	D6	IF 45.75/58.75 switching; 0: 45.75, 1: 58.75 MHz	0	
	VIF Video out gain	3	06H	D5-D7	Pin 58 IVF video-detection-wave output level adjustment	80H	
	AFT defeat	1	04H	D6	AFT output on/off (defeat) switching; 0: AFT on (non defeat), 1: Defeat	0	
	VIF defeat	1	07H	D7	VIF AGC gain normal/minimum switching; 0: AGC function, 1: Defeat (minimum gain)	0	
	Audio ATT	7	03H	D0-D6	Pin 51 audio output level adjustment	00H	
	Audio EXT	1	02H	D6	Audio internal signal and external signal input switching; 0: internal, 1: external	0	
	Audio mute	1	03H	D7	Pin 53 audio direct output on/off (mute) switching; 0: audio on (non-muted), 1: mute	0	
VIDEO	Video tone	6	04H	D0-D5	Sharpness level control	20H	V Latch
	Contrast control	7	05H	D0-D6	Contrast level control	40H	V Latch
	EXTRGB contrast clip	1	05H	D7	EXT RGB contrast lower-limit clipping on/off; 0: clipping on, 1: clipping off	0	V Latch
	C. clip level	1	02H	D5	EXT RGB contrast lower-limit clipping level switching; 0: low (20H), 1: high (40H)	0	
	Y DL time adj	2	06H	D0-D1	Y signal delay adjustment	X0H	
	Y DL fine adj	1	06H	D2	Y signal delay fine adjustment	0	
	EXT	1	06H	D3	Video input pins 41/38 switching; 0: pin 41, 1: pin 38	0	V Latch
	Y/C	1	06H	D4	Pins 38/41 composite input/YC input switching; 0: composite, 1: Y/C mode	0	V Latch
	Y SW LPF	1	13H	D5	Pin 31 (Y SW OUT) output f-characteristic switching; 0: flat, 1: LPF (fc=700 kHz)	0	
	Video tone sharp	1	02H	D3	Video tone level two level (sharp/soft) switching; 0: standard (soft), 1: sharp	0	
	Video mute	1	02H	D7	Y signal output on/off (mute) switching; 0: mute off, 1: mute	0	
	TRAP off	1	02H	D4	Y signal chroma trap on/off switching; 0: trap on, 1: trap off	0	
	TRAP fine adj	2	12H	D0-D1	Chroma trap frequency fine adjust	X0H	
	Black stretch off	1	02H	D1	Black stretch circuit on/off switching; 0: black stretch on, 1: black stretch off	0	
	Black stretch charge	2	14H	D4-D5	Black stretch charge time constant adjustment	0XH	
	Black stretch discharge	2	14H	D6-D7	Black stretch discharge time constant adjustment	0XH	
	Gamma control	2	12H	D2-D3	Gamma level adjustment	X0H	
CHROMA	Tint control	7	07H	D0-D6	Hue control	40H	V Latch
	Color control	7	08H	D0-D6	Color level control	40H	V Latch
	Take off	1	02H	D0	Chroma BPF take-off function on/off switching; 0: BPF; 1: take off	0	
	US/JPN SW	1	15H	D1-D3	US mode/JPN mode switching; 100: US mode, 011: JPN mode	0	
	Killer level	1	15H	D0	Colorkiller sensitivity switching (active shallow direction); 0: 41 dB, 1: 34 dB	0	
	Fsc	1	09H	D5	X'tal oscillation circuit forced free-running mode; 0: off, 1: free-running	0	

Bus Functions (cont)

WRITE (cont)

	FUNCTION	BIT	SUB ADD	DATA	DISCRIPTION	INI- TIAL	NOTE
RGB	Brightness control	8	0AH	D0-D7	Bright level control	80H	V Latch
	Driver (R)	7	0BH	D0-D6	R output level control	40H	
	Driver (B)	7	0CH	D0-D6	B output level control	40H	
	Cut off (R)	8	0DH	D0-D7	R output DC level control	80H	
	Cut off (B)	8	0EH	D0-D7	G output DC level control	80H	
	Cut off (B)	8	0FH	D0-D7	B output DC level control	80H	
	Blue back	1	08H	D7	Blue back screen on/off switching; 0: off, 1: blue back	0	
	White back	1	10H	D7	White raster on/off switching; 0: off, 1: white back	0	
	ABCL	1	02H	D2	ABCL on/off switching; 0: off, 1: ABCL on	0	
	ABCL gain	1	04H	D7	ABCL sensitivity low/high switching; 0: low, 1: hi	0	
	OSD level	1	15H	D5	OSD level (70%/90%) switching; 0: 70%, 1: 90%	0	
	HTONE SW	1	09H	D4	Halftone on/off switching; 0: off, 1: halftone	0	
	Analog OSD	1	15H	D4	OSD input digital/analog switching; 0: digital, 1: analog	0	
	DEF	AFC2 H phase	5	16H	D0-D4	Screen horizontal position adjustment	90H
Ramp stop		1	09H	D6	Pin 5 VOUT (ramp/pulse) forced stop mode (when stopped, pin 5 at DC GND level); 0: VOUT, 1: STOP	0	
Service SW		1	13H	D3	Vertical output on/off switching; 0: vertical output on, 1: vertical output off	0	
H start		1	13H	D4	Horizontal output out/stop switching; 0: stop, 1: H out	0	
AFC 1 gain		1	15H	D7	Horizontal AFC gain a high/low switching; 0: low, 1: hi	0	
AFC 2 gain		1	15H	D6	Horizontal AFC2 gain high/low switching; 0: high, 1: low	0	
H VCO adj		3	10H	D0-D2	H VCO free-running frequency adjustment	24H	
V shift		3	13H	D0-D2	Vertical ramp start timing adjustment	X0H	
V-size		6	11H	D0-D5	Vertical ramp amplitude adjustment	20H	
H-free		1	13H	D7	Horizontal output forced free-running mode on/off switching; 0: off, 1: horizontal free-running	0	
V-free		1	10H	D6	Vertical output forced free-running mode on/off switching; 0: off, 1: vertical free-running	0	
S slice down 1		1	14H	D2	Sync detection slice level (50%/30%) switching; 0: 50%, 1: 30%	0	
S slice down 2		1	14H	D3	Sync detection slice level (50%/40%) switching; 0: 50%, 1: 40%	0	
Audio slice down		1	16H	D6	Sync detection slice level (50%/40%) switching during image period; 0: slice level fixed, 1: slice level reduced	0	
FBP Vth L		1	16H	D5	Pin 10 (FBP in) slice level switching during image period; 0: Vth = 2V (HBLK width: narrow), 1: Vth = 1 V (HBLK width: wide)	0	
HV BLK OFF		1	09H	D7	Horizontal/vertical blanking on/off switching; 0: blanking on, 1: blanking off	0	
V SYNK DET		1	16H	D7	Vertical minimum sync detection width switching; 0: sync detect width =18 μs, 1: sync detect width =14 μs	90H	
1 window		1	13H	D6	Vertical sync detection switching (1 window/2 window s); 0: 2 windows, 1: 1 window	0	
BGPFBP OFF		1	19H	D7	Internal BGP on/off switching when no FBP input; 0: BGP on, 1: BGP off	0	
VREF INT		1	1CH	D6	Interface/non-interface switching at vertical free-running	04H	
VBLK SHIFT ON		1	1CH	D3	0: Normal (VBLK shifts by VSHIFT), 1: Vertical blanking width can be setted by un-interlocking VSHIFT	04H	
VBLK SHIFT		3	1CH	D0-D2	D0-D2: VBLK SHIFT (Initial value: 100=4)	04H	
Monitoring		4	12H	D4-D7	Pin 18 intelligent monitoring mode switching	0XH	
Test1		1	18H	D6-D7	NO use for Customer (Test bit)	0	
Test2		1	19H	D6	NO use for Customer (Test bit)	0	
Test3		1	1AH	D6-D7	NO use for Customer (Test bit)	0	
Test4		1	1CH	D6	NO use for Customer (Test bit)	04H	

READ

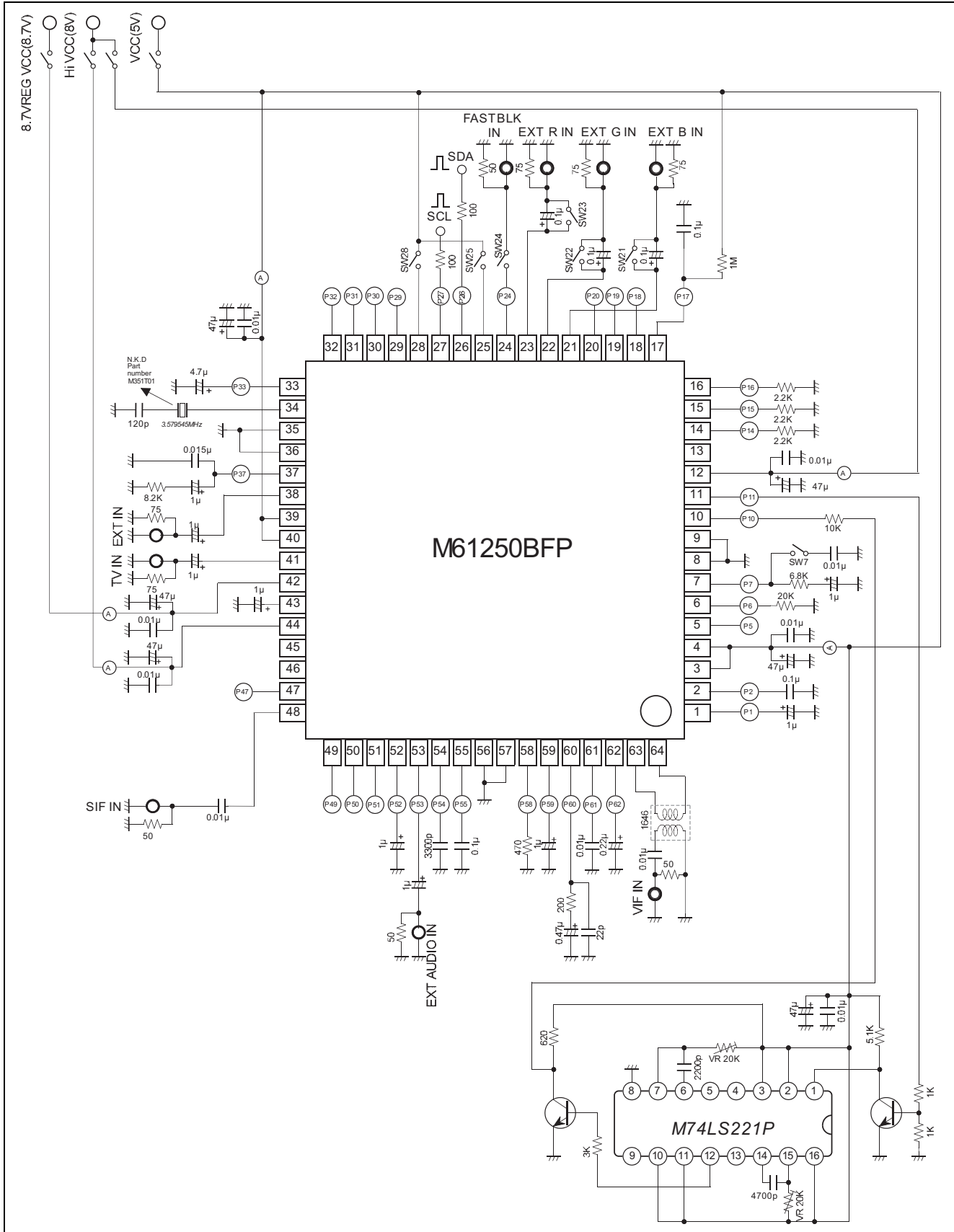
FUNCTION	BIT	SUB ADD	DATA	DISCRIPTION
KILLERB	1	00H	D7	Colorkiller information output; "1" when killer off
AFT0	1	00H	D3	AFT information output (See note 1)
AFT1	1	00H	D2	AFT information output (See note 1)
HCOINB	1	00H	D1	Horizontal sync detection; "1" when asynchronous
FM STDETB	1	00H	D6	FM radio mode detection; "1" when not detected
VCOINB	1	00H	D5	Vertical sync detection; "1" when asynchronous
STDETB	1	00H	D4	TF mode detection; "1" when not detected

Note: 1. <READ BYTE: AFT OUTPUT>

AFT0/AFT1



Test Circuits



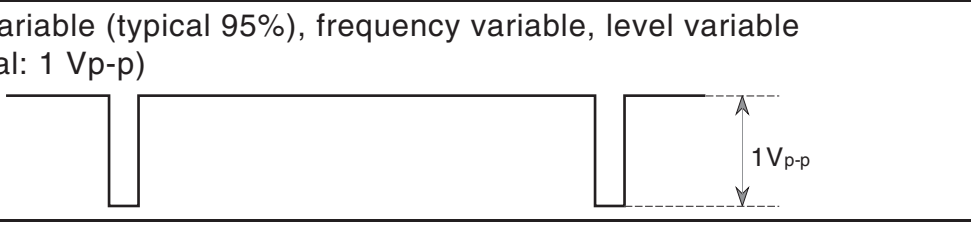
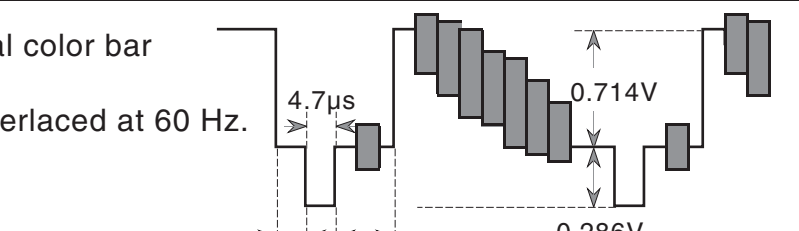

Input Signals**1. 10.1 VIF/SIF Block**

SG No.	Signal description (50 Ω termination)
SG1	fo = 45.75 MHz, 90 dB μ , fm = 20 kHz, AM 77.8%
SG2	fo = 58.75 MHz, 90 dB μ , fm = 20 kHz, AM 77.8%
SG3	fo = 45.75 MHz, 90 dB μ , CW
SG4	f1 = 45.75 MHz, 90 dB μ , CW f2 = 45.75 \pm 4.5MHz, 70 dB μ , CW
SG5	fo = 45.75 MHz, amplitude width variable, fm = 20 kHz, AM 77.8%
SG6	fo = 45.75 MHz, amplitude width variable, fm = 20 kHz, AM 16%
SG7	fo = 45.75 MHz, 80 dB μ , fm = 20 kHz, CW
SG8	fo = 45.75 MHz, 110 dB μ , fm = 20 kHz, CW
SG9	fo = 40.75 to 50.75 MHz (frequency variable), 90 dB μ , CW
SG10	fo = 45.75 MHz, 90 dB μ , CW
SG11	fo = 45.75 MHz, 90 dB μ , CW
SG12	fo = 53.75 to 63.75 MHz (frequency variable), 90 dB μ , CW
SG13	f1 = 45.75 MHz, 90 dB μ , RED raster signal, AM = 87.5% video modulation, f2 = 4.5 \pm 4.5MHz, CW, P/S = 20 dB
SG14	fo = 45.75 MHz, standard 10-step wave, sync rate: 28.6%, AM = 87.5% video modulation, sync chip level: 90 dB μ
SG15	fo = 45.75 MHz, 93 dB μ , CW
SG16	fo = 45.75 MHz, 73 dB μ , CW
SG17	fo = 4.5 MHz, 100 dB μ , fm = 400 Hz, FM \pm 25 kHz dev.
SG18	fo = 4.5 MHz, 100 dB μ , fm = 400 kHz, AM 30%
SG19	fo = 4.5 MHz, 100 dB μ , CW
SG20	fo = 400 Hz, 500 mVrms, CW
SG21	fo = 0.5 to 8.5 MHz, 100 dB μ , fm = 400 kHz, FM \pm 25 kHz dev.

2. Video/Chroma/RGB/DEF Block

SG No.	Signal description (75Ω termination)	
SG. A	<p>NTSC format APL 100% typical video signal. Vertical signal is interlaced at 60 Hz.</p>	
SG. B	<p>In the SG.A signal, the Lumi. signal frequency and amplitude can be changed. However, typical amplitude is 0.714 Vp-p. In the figure on the right, the Lumi. signal is represented by f.</p>	
SG. C	<p>NTSC typical monochrome video signal. Vertical signal is interlaced at 60 Hz.</p>	
SG. D	<p>NTSC format video signal; APL variable. Vertical signal is interlaced at 60 Hz.</p>	
SG. E	<p>NTSC format monochrome video signal. In the SG.C signal, the burst and chroma part frequency and amplitude can be changed. Vertical signal is interlaced at 60 Hz.</p> <p>(Typical state: Veb=0.286V, Vec=0.572V feb=fec=3.579545MHz)</p>	
SG. F	<p>Fast blanking signal; synchronized with video input signal.</p> <p>Fast blanking signal; synchronized with video input signal.</p>	

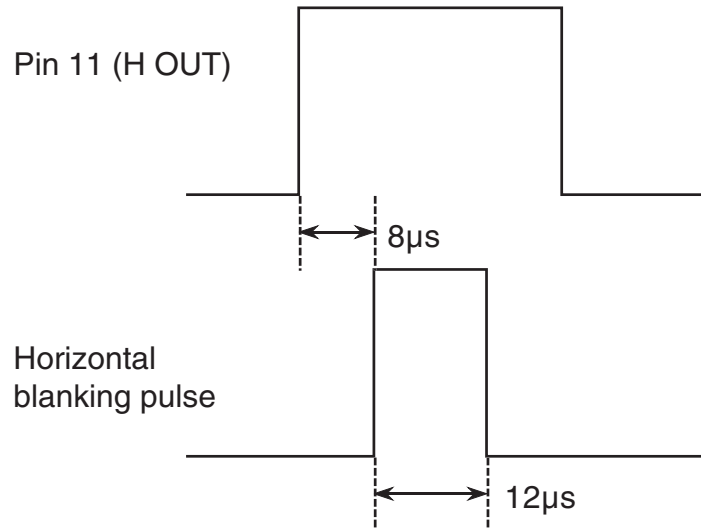
2. Video/Chroma/RGB/DEF Block (cont)

SG No.	Signal description (75Ω termination)
SG. G	NTSC format rainbow color bar video signal. Vertical signal is interlaced at 60 Hz.
SG. H	Duty 90%, variable frequency, variable level. (Typical: 1 V _{p-p}) 
SG. I	Duty variable (typical 95%), frequency variable, level variable (Typical: 1 V _{p-p}) 
SG. J	NTSC format typical color bar video signal; vertical signal is interlaced at 60 Hz. 
SG. K	NTSC format, typical 8-step wave signal; vertical signal is interlaced at 60 Hz.

Setup instruction for evaluation PCB

1. Horizontal blanking pulse adjustment

The horizontal blanking pulse timing and pulse width are adjusted using the variable resistances of a one-shot multivibrator, as shown below.

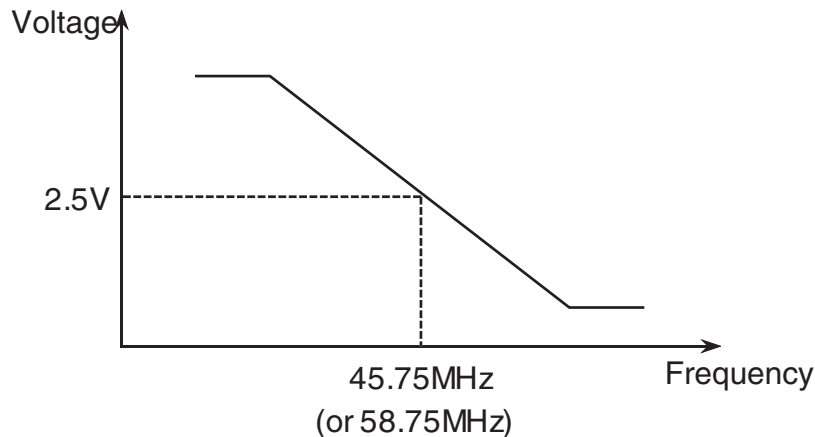


The timing is adjusted to 8 µs using the pin 15 variable resistance of the M74LS221P TTL IC. Also, the pulse width is adjusted to 12 µs using the pin 7 variable resistance.

2. VIF VOC adjustment

Before carrying out the M61250BFP measurements, the VIF VCO should be adjusted using the following procedure.

- (1) Input the I²C bus data for the VIF frequency (01H D6) based on the IF frequency. (45.75 MHz: 0, 58.75 MHz: 1)
- (2) Input the I²C bus data for VIF Defeat ON (07H D7 = 1).
- (3) Adjust the I²C bus data for the VCO control (01H D0 – D5) so that the voltage of Pin 2 (AFT OUT) is closest to 2.5 V.
- (4) Input the I²C bus data for VIF Defeat OFF (07H D7 = 0).



3. H VCO adjustment

Prior to measurement of the M61250BFP, the following method is used for H VCO adjustment.

- (1) The H VCO control I²C bus data (1 CH D0-D3) is adjusted, and the pin 11 (H OUT) frequency is set to approx. 15.734 kHz.

Method of Measurement of Electrical Characteristics

VIF block

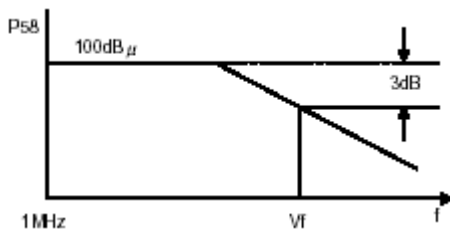
- P/N: Video S/N

1. Input SG3, and measure the rms value (noise value) for the signal output from pin 58.
2. The P/N is defined as follows.

$$P/N = 20 \log \frac{V_0 \text{ measured value (Vp-p)} \times 10^3 \times 0.7}{\text{Noise measured value (mVrms)} \quad (\text{dB})}$$

- Vf: Video frequency characteristic

1. Input SG4, and adjust the f_2 frequency so that the 1 MHz beat component is output to pin 58.
2. Adjust the voltage applied to pin 62 so that the 1 MHz beat component at pin 62 is 100 dB μ .
3. Gradually reduce the f_2 frequency, and measure the frequency at which the beat component is 3 dB lower than the level at 1 MHz.



- Vin min: Input sensitivity

1. Lower the level of SG5 so that the input level is 3 dB lower than the value measured under video-detection-wave output” for the V_0 item.

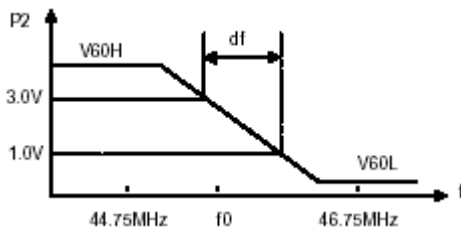
- Vin max: Maximum allowable input

1. Input SG6 at 90 dB μ .
2. The output level of Pin 58 at this point should be V_A . Increase the amplitude of SG6 so that the input level indicates an output level for Pin 58 that is 3 dB lower than V_A .

- μ AFT: AFT detection sensitivity

V2H: AFT maximum voltage

V2L: AFT minimum voltage



μ AFT is defined as follows.

$$\mu\text{AFT} = \frac{(3.0 - 1.0) \times 10^3 \text{ mV}}{df \text{ KHz}} \quad (\text{mV/KHz})$$

M61250BFP

- IM: Inter-modulation

1. Input SG13 to Pins 63 and 64.
2. Measure the 0.92 MHz component and 3.58 MHz component of the pin 58 output.
3. IM is defined as follows.

$$IM = 20 \log \frac{0.92 \text{ MHz component}}{3.58 \text{ MHz component}} \quad (\text{dB})$$

- DLPH: RF AGC delay maximum point
- DLPL: RF AGC delay minimum point

1. Input SG5 to pins 63 and 64.
2. Change the amplitude of SG5 and measure the level at which the voltage of pin 59 is 2.5 V.

SIF block

- LIM: Input limiting sensitivity

Gradually decrease the input level of SG17, and measure the input level at the point when the 400 Hz component of Pin 58 is 3 dB lower than VoAF.

- AMR: AMR

1. Measure the 400 Hz component for Pin 54 and set it as Vam.
2. AMR is defined as follows.

$$AMR = 20 \log \frac{VoAF \text{ (mVrms)}}{Vam \text{ (mVrms)}} \quad (\text{dB})$$

- AFSN: AF S/N

1. Measure the noise (20 Hz to 100 kHz) of the Pin 51 output.
2. AF S/N is defined as follows.

$$AF \text{ S/N} = 20 \log \frac{VoAF \text{ max}}{\text{Measured value}} \quad (\text{dB})$$

Video clock

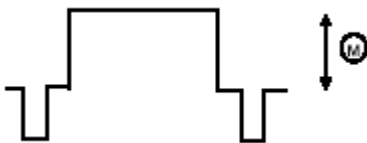
- 2AGTV: Video SW output level (TV input)
- 2AGEV: Video SW output level (External input)

1. Input SG.A to pin 41 (2AGTV) or pin 38 (2AGEV).
2. The amplitude (p-p) at pin 31 is measured.

*In order to select TV or external input, use the subaddress 06H.

- Ymax: Maximum video output

1. Input SG.A to pin 38.
2. Measure the amplitude (p-p) other than the blanking part of the output of pins 14, 15, 16.



- **FYB: Video frequency characteristic**

1. Input SG.B (5 MHz, 0.4 V_{p-p}) to pin 38.
2. Measure the amplitude (p-p) other than the blanking part of the output of pins 14, 15, 16, take the result to be YB.
3. FYB is defined as follows.

$$FYB = 20 \log \frac{YB (V_{p-p})}{GY (V_{p-p})} \quad (\text{dB})$$

- **CRF1: Chroma trap attenuation 1 (normal R/G/B output)**

TRF maximum chroma trap attenuation

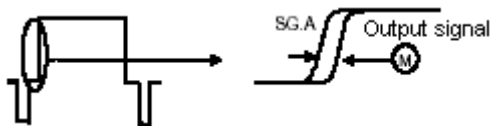
1. Input SG.C to pin 38, measure the 3.58 MHz frequency level with TRAP ON/OFF (02H D4) DATA 1, take this to be N₀.
2. Also measure the level with TRAP ON/OFF (02H D4) DATA 0.
3. CRF1 is defined as follows.

$$CRF1 = 20 \log \frac{\text{Measured value (mV}_{p-p}\text{)}}{N_0 \text{ (mV}_{p-p}\text{)}} \quad (\text{dB})$$

4. Take the minimum value of CRF1 when the I²C BUS data of the TRAP fine ADJ (12H D0/D1) is adjusted to be TRF.

- **YDL1: YDL time 1**

1. Input SG.A to pin 38.
2. Measure the delay time relative to the input signal of pins 14, 15, 16.



The delay time at 50% rise level is measured.

- **YDL2, 3, 4: YDL time 2, 3, 4**

1. Input SG.A to pin 38.
2. Measure the delay time of the input signal and the pin 14, 15, 16 output signals.
3. YDL2, YDL3, YDL4 are defined as follows.

$$YDL2 = \text{measured value (ns)} - YDL1 \text{ (measured value)}$$

$$YDL3 = \text{measured value (ns)} - YDL2 \text{ (measured value)}$$

$$YDL4 = \text{measured value (ns)} - YDL3 \text{ (measured value)}$$

- **GTmax: Video tone control characteristic 2**

1. Input SG.B (f = 2.5 MHz) to pin 38.
2. The output amplitude of pins 14, 15, 16 when the video tone data is at the center (20 H) is taken to be GT_{nor}.
3. The output amplitude of pins 14, 15, 16 when the video tone data is maximum is measured.
4. GTmax is defined as follows.

$$GTmax = 20 \log \frac{\text{Measured value (V}_{p-p}\text{)}}{GT_{nor} \text{ (mV}_{p-p}\text{)}} \quad (\text{dB})$$

- GTmin: video tone control characteristic 3

1. Input SG.B (f=2.5 MHz) to pin 38.
2. The output amplitude of pins 14, 15, 16 when the video tone data is at the center (20 H) is taken to be GTnor.
3. The output amplitude of pins 14, 15, 16 when the video tone data is minimum is measured.
4. GTmin is defined as follows.

$$GTmin = 20 \log \frac{\text{Measured value (Vp-p)}}{GTnor \text{ (mVp-p)}} \quad (\text{dB})$$

- GT2M: Video tone control characteristic 4

1. Take pin 14, 15, 16 output amplitude when input signal frequency is 2.5 MHz to be GTnor.
2. Input SG.B (f = 2 MHz) to pin 38.
3. Measure pin 14, 15, 16 output amplitude.
4. GT2M is defined as follows.

$$GT2M = 20 \log \frac{\text{Measured value (Vp-p)}}{GTnor \text{ (mVp-p)}} \quad (\text{dB})$$

- GT5M: Video tone control characteristic 5

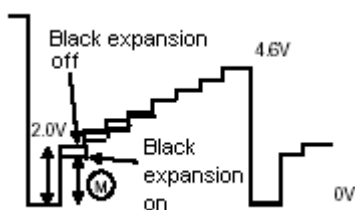
1. Take pin 14, 15, 16 output amplitude when input signal frequency is 2.5 MHz to be GTnor.
2. Input SG.B (f = 2 MHz) to pin 38.
3. Measure pin 14, 15, 16 output amplitude.
4. GT5M is defined as follows.

$$GT5M = 20 \log \frac{\text{Measured value (Vp-p)}}{GTnor \text{ (mVp-p)}} \quad (\text{dB})$$

- BLS: black stretch characteristic

1. Input SG.K to pin 38.
2. With black stretch off (02H D1 = 1), adjust the contrast (05H) and brightness (0AH), and set the pin 14, 15, 16 output level of the first stage (lowest stage) to 2.0 V, and the output level of the eighth stage (highest stage) to 4.6 V.
3. Change black stretch to on (02H D1 = 0), and measure the pin 14, 15, 16 first stage output level.
4. BLS is defined as follows.

$$BLS = 2.0 - \text{measured value (V)}$$



- VMF: Video mute function

1. Input SG.A to pin 38.
2. With the mute switch (02H D7) on "VMFon", off "VMFoff", measure the output amplitude.
3. VMF is defined as follows.

$$VMF = 20 \log \frac{VMFon \text{ (Vp-p)}}{VMFoff \text{ (Vp-p)}} \quad (\text{dB})$$

Chroma block

- CnorR: Chroma typical output (R-Y)
- CnorB: Chroma typical output (B-Y)
- 1. Input SG.C to pin 38.
- 2. When "test mode" I²C data is 18H D6=1, 18H D7=1 and 19H D6=1 and when "test mode" I²C data is 18H D6=0, 18H D7=1 and 19H D6=1, take the pin 59 output amplitude to be the chroma typical output (R-Y) and chroma typical output (B-Y), respectively.

- ACC1: ACC characteristic 1
- 1. Input SG.E (eb=570 mV: level + 6 dB) to pin 38.
- 2. Measure the pin 59 output amplitude.
- 3. ACC1 is defined as follows.

$$\text{ACC1} = 20 \log \frac{\text{measured value (mVp-p)}}{\text{chroma typical output 1 (mVp-p)}} \quad (\text{dB})$$

- ACC2: ACC characteristic 2
- 1. Input SG.E (input level: -18 dB) to pin 38.
- 2. Measure the pin 59 output amplitude.
- 3. ACC2 is defined as follows.

$$\text{ACC2} = 20 \log \frac{\text{measured value (mVp-p)}}{\text{chroma typical output 1 (mVp-p)}} \quad (\text{dB})$$

- OV: Chroma overload characteristic
- 1. Input SG.E (eb=800 mVp-p) to pin 38.
- 2. Measure the pin 59 output amplitude.
- 3. OV is defined as follows.

$$\text{OV} = 20 \log \frac{\text{measured value (mVp-p)}}{\text{chroma typical output 1 (mVp-p)}} \quad (\text{dB})$$

- VikN: Killer operation input level
- 1. Input SG.E (variable level) at input level 0 dB to pin 38.
- 2. While monitoring the pin 59 output amplitude, lower the input level, and measure the input level when the output amplitude vanishes.

- KillP: Hue remaining with killer
- 1. Input SG.E (level: -40 dB) to pin 38.
- 2. Measure the pin 59 output amplitude.

- APCU: APC pull-in range (upper)
- APCL: APC pull-in range (lower)
- 1. Input SG.E (feb-fec-3.579545 MHz) to pin 38.
- 2. After raising the frequency until the output from pin 59 vanishes, lower the frequency, and take the point at which an output appears to be fu.
- 3. After lowering the frequency until the output from pin 59 vanishes, raise the frequency, and take the point at which an output appears to be fl.
- 4. APCU and APCL are defined as follows.

$$\text{APCU} = f_u - 3579545 \text{ Hz}$$

$$\text{APCL} = f_l - 3579545 \text{ Hz}$$

- R/BN: Demodulation ratio R-Y/B-Y

1. Input SG.E (eb = single chroma = ec + 50 kHz) to pin 38.
2. Take the pin 59 output amplitude when "test mode" I²C data is 18H D6=1, D7=1 to be VRY.
3. Take the pin 59 output amplitude when "test mode" I²C data is 18H D6=0, D7=1 to be VBY.
4. R/BN is defined as follows.

$$R/BN = \frac{VRY \text{ (mVp-p)}}{VBY \text{ (Vp-p)}} \quad (\text{dB})$$

- R/BU, G/BU: Demodulation ratio

- R/BJ, G/BJ: Demodulation ratio

1. Input SG.J to pin 38.
2. Take the pins 14, 15, 16 output amplitude when video mute on (02H D7 = 1, D7 = 1) and US mode (15H D3 = 1) are specified to be URY, UGY, and UBY, respectively.
3. Take the pins 14, 15, 16 output amplitude when video mute on (02H D7 = 1, D7 = 1) and JPN mode (15H D1 = 1, D2=1) are specified to be JRY, JGY, and JBY, respectively.
4. R/BU, G/BU, R/BJ, and G/BJ are defined as follows.

$$R/BU = \frac{URY(Vp-p)}{UBY(Vp-p)} \quad G/BU = \frac{UGY(Vp-p)}{UBY(Vp-p)}$$

$$R/BJ = \frac{JRY(Vp-p)}{JBY(Vp-p)} \quad G/BJ = \frac{JGY(Vp-p)}{JBY(Vp-p)}$$

- R-YN: Demodulation angle

1. Input SG.E (eb = single chroma = ec + 5 kHz) to pin 38.
2. Take the pin 59 output amplitude when "test mode" I²C data is 18H D6=1, D7=1 to be VRY.
3. Take the pin 59 output amplitude when "test mode" I²C data is 18H D6=0, D7=1 to be VBY.
4. R/YN is defined as follows.

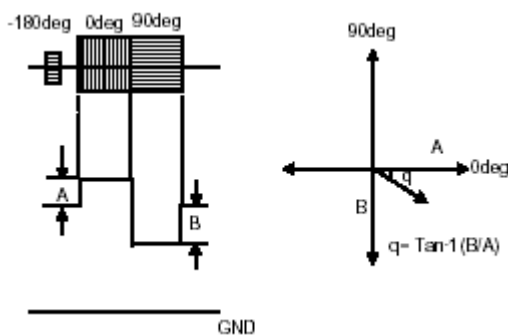
$$R-YN = \text{Tan}^{-1} \frac{VRY \times 3.8}{(VBY \times 1.9) + 45} (\text{deg})$$

*The vector is determined taking the demodulator gain into account.

- TC1: TINT control characteristic 1

- TC2: TINT control characteristic 2

1. Input SG.C (see figure below) to pin 38. Measure the absolute angle with reference to the pin 59 output voltage, referring to the figure below.



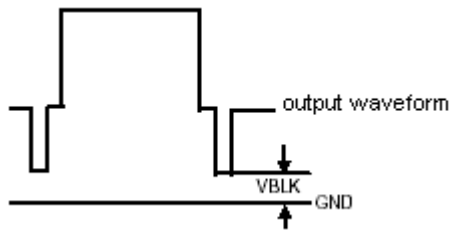
2. Take the TINT data center part (07H data 40H) to be reference angle "TC", determine the TINT DATA maximum and minimum values. TC1 and TC2 are defined as follows.

$$TC = TC_{\text{max}} - TC(\text{deg})$$

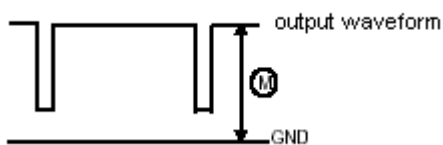
$$TC = TC - TC_{\text{min}} (\text{deg})$$

RGB interface block

- VBKL: Output blanking voltage
 1. Input SG.A to pin 38.
 2. Measure the voltage of the pin 14, 15, 16 pedestal and blanking parts.



- GYmax: Contrast control characteristic 1
- GYmin: Contrast control characteristic 2
 1. Input SG.B (f=100 kHz) to pin 38.
 2. Measure the pin 14, 15, 16 output amplitude.
- GYEnor: Contrast control characteristic 3
- GYEmin: Contrast control characteristic 4
 1. Input SG.A to pin 38.
 2. Measure the pin 14, 15, 16 output amplitude when applying 2.9 V and 0 V to pin 33.
- GYEclip: Contrast control characteristic 5
 1. Input SG.F to pins 21, 22, 23, 24.
 2. Minimize the contrast control data, and measure the output amplitude at and above the pedestal part of pins 14, 15, 16.
The amplitude of the blanking part is not measured.
- Lum nor: Brightness control characteristic 1
- Lum max: Brightness control characteristic 2
- Lum min: Brightness control characteristic 3
 1. Input SG.D (Vy=0 V) to pin 38.
 2. Measure the DC voltage other than the blanking part of the output of pins 14, 15, 16.



- D(R)1: R drive control characteristic 1
 1. Input SG.A to pin 38.
 2. Measure the pin 14 output amplitude when the drive control data is at center and is maximum, take the results to be DRnor and DRmax respectively.
 3. D(R)1 is defined as follows.

$$D(R)1 = 20 \log \frac{DR_{\max} (Vp-p)}{DR_{\text{nor}} (Vp-p)} (\text{dB})$$

- D(B)1: B drive control characteristic 1
 1. Input SG.A to pin 38.
 2. Measure the pin 16 output amplitude when the drive control data is at center and is maximum, take the results to be DBnor and DBmax respectively.
 3. D(B)1 is defined as follows.

$$D(B)1 = 20 \log \frac{DB_{\max} (V_{p-p})}{DB_{\text{nor}} (V_{p-p})} (\text{dB})$$

- D(R)2: R drive control characteristic 2

1. Input SG.A to pin 38.
2. Measure the pin 14 output amplitude when the drive control data is at center and is minimum, take the results to be DRnor and DRmin respectively.
3. D(R)2 is defined as follows.

$$D(R)2 = 20 \log \frac{DR_{\min} (V_{p-p})}{DR_{\text{nor}} (V_{p-p})} (\text{dB})$$

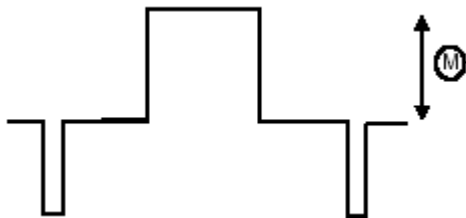
- D(B)2: R drive control characteristic 2

1. Input SG.A to pin 38.
2. Measure the pin 16 output amplitude when the drive control data is at center and is minimum, take the results to be DBnor and DBmin respectively.
3. D(B)2 is defined as follows.

$$D(B)2 = 20 \log \frac{DB_{\min} (V_{p-p})}{DB_{\text{nor}} (V_{p-p})} (\text{dB})$$

- EXD(R): Digital OSD(R) input/output characteristic
- EXD(G): Digital OSD(G) input/output characteristic
- EXD(B): Digital OSD(B) input/output characteristic

1. Input SG.F (Vosd=1.0 V) to pins 21, 22, 23, 14.
2. Measure the output amplitude at and above the pedestal part in pins 14, 15, 16. The amplitude of the blanking part is not measured.



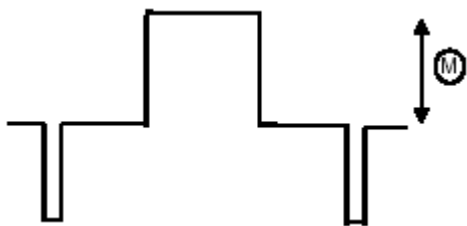
- EXD(R-G): Digital OSD (R-G) amplitude difference
 - EXD(G-B): Digital OSD (G-B) amplitude difference
 - EXD(B-R): Digital OSD (B-R) amplitude difference
1. EXD(R-G), EXD(G-B) and EXD(B-R) are defined as follows.

$$EXD(R-G) = EXD(R) - EXD(G)$$

$$EXD(G-B) = EXD(G) - EXD(B)$$

$$EXD(B-R) = EXD(B) - EXD(R)$$

- EXA(R): Analog OSD(R) input/output characteristic
 - EXA(G): Analog OSD(G) input/output characteristic
 - EXA(B): Analog OSD(B) input/output characteristic
1. Input SG.F (V_{osd}=1.0 V) to pins 21, 22, 23, 14.
 2. Measure the output amplitude at and above the pedestal part in pins 14, 15, 16. The amplitude of the blanking part is not measured.



- EXA(R-G): Analog OSD (R-G) amplitude difference
 - EXA(G-B): Analog OSD (G-B) amplitude difference
 - EXA(B-R): Analog OSD (B-R) amplitude difference
1. EXA(R-G), EXA(G-B) and EXA(B-R) are defined as follows.

$$EXA(R-G) = EXA(R) - EXA(G)$$

$$EXA(G-B) = EXA(G) - EXA(B)$$

$$EXA(B-R) = EXA(B) - EXA(R)$$

- C(R)1: R cutoff characteristic 1
 - C(G)1: G cutoff characteristic 1
 - C(B)1: B cutoff characteristic 1
 - C(R)2: R cutoff characteristic 2
 - C(G)2: G cutoff characteristic 2
 - C(B)2: B cutoff characteristic 2
1. Input SG.D (V_y=0 V) to pin 38.
 2. Measure the DC voltage of other than the blanking part in the outputs of pins 14, 15, 16.

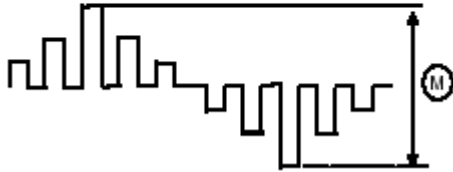
- Ccon1: color control characteristic 1
 - Ccon2: color control characteristic 2
 - Ccon3: color control characteristic 3
1. Input SG.C to pin 38.
 2. Measure the output amplitudes of pins 14, 15, 16 when IIC DATA 08H=40h, take this to be Ccon0.
 3. Measure the output amplitudes of pins 14, 15, 16 under each set of conditions.
 4. Ccon1, Ccon2, Ccon3 are defined as follows.

$$Ccon1, Ccon2, Ccon3 = 20 \log \frac{\text{measured value (Vp-p)}}{Ccon0 (Vp-p)} \quad (\text{dB})$$

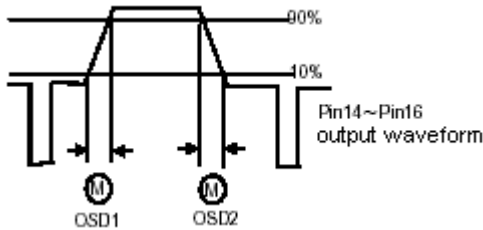
- MTXRB: Matrix ratio R/B
 - MTXGB: Matrix ratio G/B
1. Input SG.G (rainbow color bar) to pin 38.
 2. Measure the output amplitude when pins 14, 15, 16 are respectively VR, VG, VB.
 3. MTXRB, MTXGB are defined as follows.

$$MTXRB = \frac{VR (V_{p-p})}{VB (V_{p-p})}$$

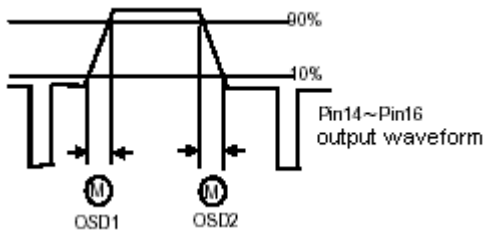
$$MTXGB = \frac{VG (V_{p-p})}{VB (V_{p-p})}$$



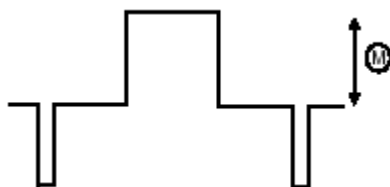
- DOSD1: Digital OSD switching characteristic 1
 - DOSD2: Digital OSD switching characteristic 2
1. Input SG.F (Vosd=1.0 V) to pins 21, 22, 23, 24.
 2. Measure the rise time and fall time of the output signals of pins 14, 15, 16 at and above pedestal level. The blanking part is not measured.



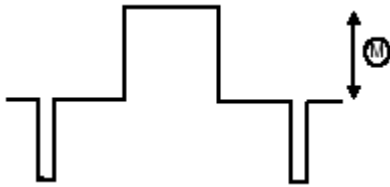
- AOSD1: Analog OSD switching characteristic 1
 - AOSD2: Analog OSD switching characteristic 2
1. Input SG.F (Vosd=1.0 V) to pins 21, 22, 23, 24.
 2. Measure the rise time and fall time of the output signals of pins 14, 15, 16 at and above pedestal level. The blanking part is not measured.



- BB(R): Blue back function (R)
 - BB(G): Blue back function (G)
 - BB(B): Blue back function (B)
1. Input SG.A to pin 38.
 2. Measure the output amplitude (p-p) of pins 14, 15, 16 other than the blanking part.



- WB: White raster function
 1. Input SG.A to pin 38.
 2. Measure the output amplitude (p-p) of pins 14, 15, 16 other than the blanking part.

**Deflection block**

- fH1: Horizontal free-running frequency 1
 - fH2: Horizontal free-running frequency 2
 - fH3: Horizontal free-running frequency 3
- Measure the frequency of pin 11 with no input.

- Hfree: Forced horizontal free-running operation
 1. Input SG.A to pin 38.
 2. Set H-FREE CONTROL DATA to on, measure the frequency at pin 11.

- FPHU: Horizontal pull-in range (upper)
- FPHL: Horizontal pull-in range (lower)
 1. Input SG.H to pin 38.
 2. Change the frequency of SG.H, measure the frequency range for which the pin 11 output signal and pin 38 input signal are pulled in, with respect to the video signal horizontal frequency.

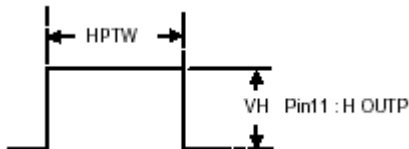
- HPT1: Horizontal pulse timing 1



- HPT2: Horizontal pulse timing 2
 1. Measure the horizontal pulse timing using the method for HPT1.
 2. Typical

$$\text{HPT2} = (\text{measured value}) - \text{HPT1}$$

- HPTW: Horizontal pulse width
- VH: Horizontal pulse amplitude



- HSTA: Horizontal pulse stop operation

Confirm that when H.START SW OFF (0FH:D7=0), the horizontal output goes low.

- AFCG: AFC gain operation

1. Measure the pin 7 output amplitude during AFC switching, taking the result during SW ON to be AFCon, and during SW OFF to be AFCoff.
2. AFCG is defined as follows.

$$\text{AFCG} = 20 \log \frac{\text{AFCon (Vp-p)}}{\text{AFCoff (Vp-p)}} \text{ (dB)}$$

- fV: Vertical free-running frequency

Measure the pin 5 output frequency with no input.

- Vfree: Forced vertical free-running operation

1. Input SG.A to pin 38.
2. Set V-FREE CONTROL DATA to on, measure the pin 5 output amplitude.

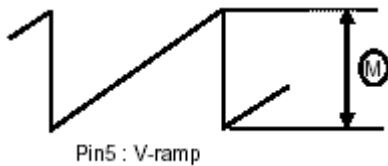
- SCV: Service mode operation

Measure the pin 5 output DC voltage with the service switch on.

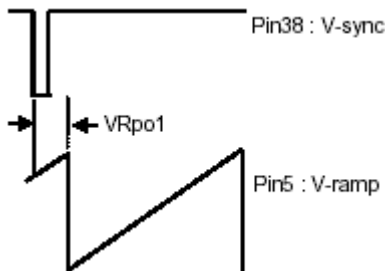
- FPVU: Vertical pull-in frequency (upper)
- FVPL: Vertical pull-in frequency (lower)

Change the SG.H vertical frequency, and measure the frequency when the pin 5 output waveform is pulled in.

- VRsi: Vertical ramp size
- VRsc1: Vertical ramp size control range 1
- VRsc2: Vertical ramp size control range 2



- VRpo1: Vertical ramp position control range 1

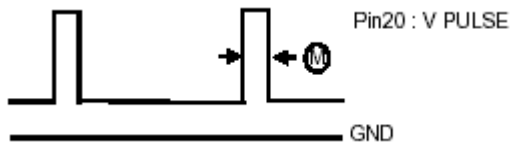


- VRpo2: Vertical ramp position control range 2

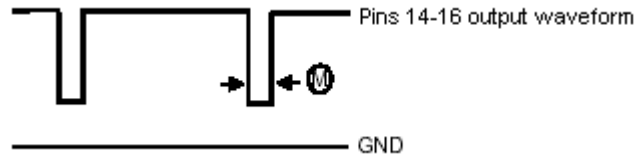
1. Measure the vertical ramp timing using the same method as for VRpo1.
2. VRpo2 is defined as follows.

$$\text{VRpo2} = (\text{measured value}) - \text{VRpo1}$$

- VW: Vertical pulse width



- VBLKW: Vertical BLK width



- WVSS: Minimum width at minimum sync operation

Reduce the width of the SG.I signal, and measure the input signal width when the pin 5 output waveform pull-in is lost.

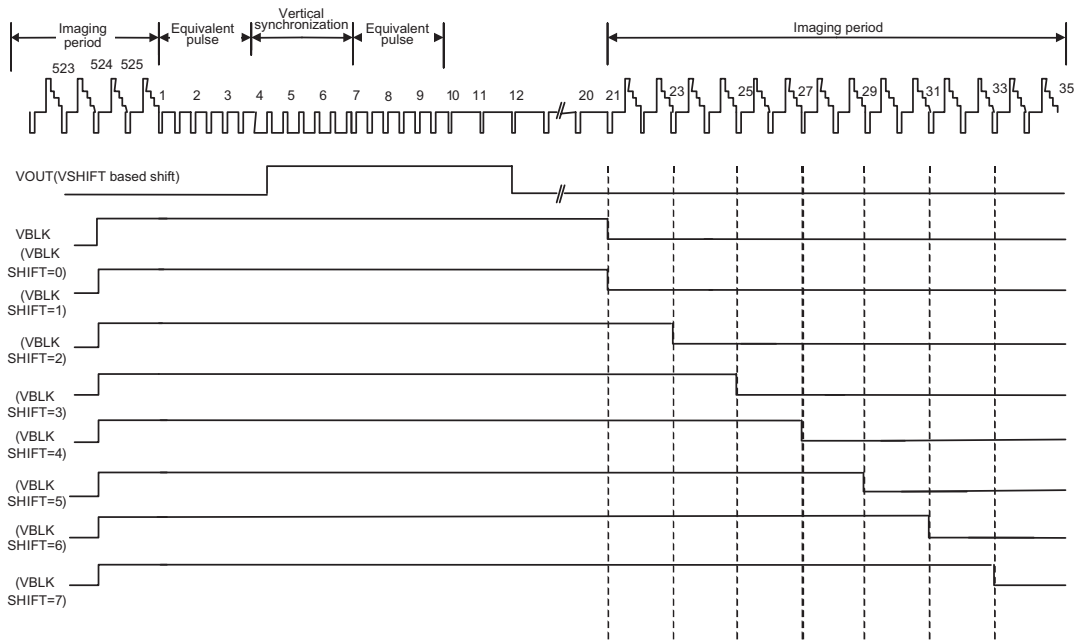
The following function is added to the M61250BFP (VBLKWVS1 to VBLKWVS3)

The vertical blanking width can be specified independently of VSHIFT.

Note, however, that it operates in the same way as conventional products in the initial state.

The following bits are added to the I²C register.

- VBLK SHIFT ON (1CH D3) Initial value = 0
 - 0: Shifts the VBLK based on the conventional SHIFT
 - 1: Shifts the VBLK based on the VBLK SHIFT.
- VBLK SHIFT (1CH D2 to 1CH D0) Initial value = 4
 - 0: VBLK period is 260 H to 21 H.
 - 1: VBLK period is 260 H to 21 H.
 - 2: VBLK period is 260 H to 23 H.
 - 3: VBLK period is 260 H to 25 H.
 - 4: VBLK period is 260 H to 27 H.
 - 5: VBLK period is 260 H to 29 H.
 - 6: VBLK period is 260 H to 31 H.
 - 7: VBLK period is 260 H to 33 H.



- An image may be output during the V blanking period according to the VSHIFT value. In this case, the VBLK should be shifted in order not to output the image during the blanking period. Carefully consider this because the output condition changes according to the circuit connected externally.

Important Information

- Each application should be thoroughly studied and evaluated before making a decision.
- 47 mF and higher electrolytic capacitors and 0.01 mF and higher ceramic capacitors should be connected in parallel between each of the power supply pins (3, 4, 12, 39, 42, 44) and ground pin. In addition, it is recommended that the connectors be made as close to the IC power supply pins as possible.
- The C-SYNC output operation of the intelligent monitor (18 pins) cannot be guaranteed at Hfree (13H: D7 = 1) .
- When purchasing I2C bus components, a license to use these components within a 12C bus system is provided under the 12C patent rights of Philips Corp.
However, the bus system must conform to the 12C specifications stipulated by Philips.

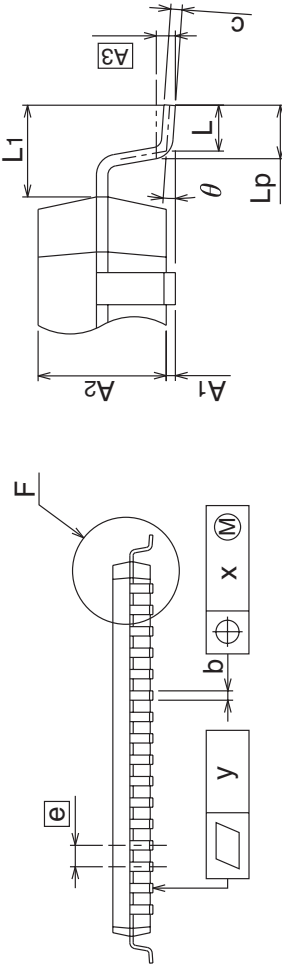
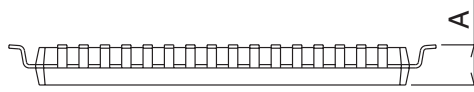
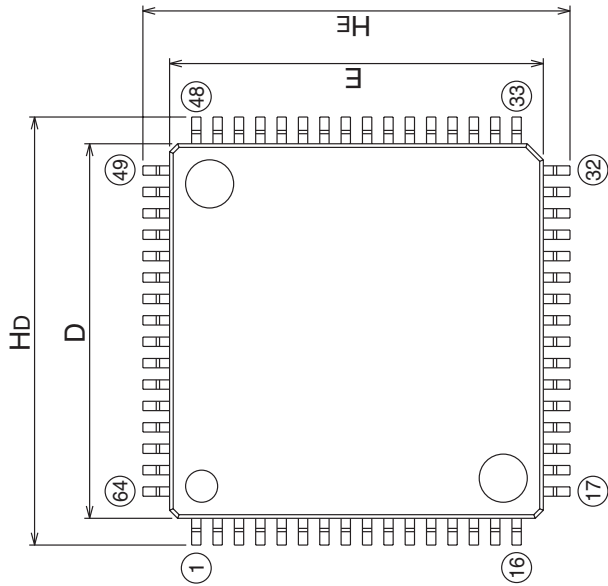
Package Dimensions

64P6U-A

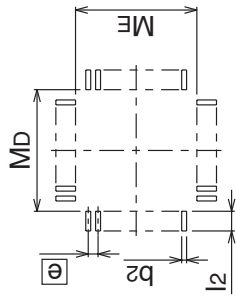
(MMP)

Plastic 64pin 14 14mm body LQFP

EIAJ Package Code LQFP64-P-1414-0.8	JEDEC Code —	Weight(g)	Lead Material Cu Alloy
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Detail F



Recommended Mount Pad

Symbol	Dimension in Millimeters		
	Min	Norm	Max
A	—	—	1.7
A1	0	0.1	0.2
A2	—	1.4	—
b	0.32	0.37	0.45
c	0.105	0.125	0.175
D	13.9	14.0	14.1
E	13.9	14.0	14.1
e	—	0.8	—
HD	15.8	16.0	16.2
HE	15.8	16.0	16.2
L	0.3	0.5	0.7
L1	—	1.0	—
Lp	0.45	0.6	0.75
A3	—	0.25	—
x	—	—	0.2
y	—	—	0.1
θ	0°	—	8°
b2	—	0.5	—
l2	0.95	—	—
MD	—	14.4	—
ME	—	14.4	—

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Renesas Technology America, Inc.
450 Holger Way, San Jose, CA 95134-1368, U.S.A
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Renesas Technology Hong Kong Ltd.
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26/F., Ruijin Building, No.205 Maoming Road (S), Shanghai 200020, China
Tel: <86> (21) 6472-1001, Fax: <86> (21) 6415-2952

Renesas Technology Singapore Pte. Ltd.
1, Harbour Front Avenue, #06-10, Keppel Bay Tower, Singapore 098632
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